IXYS

Preliminary Technical Information

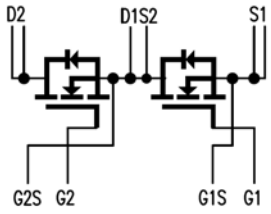
Polar3™ HiperFET™ Power MOSFET

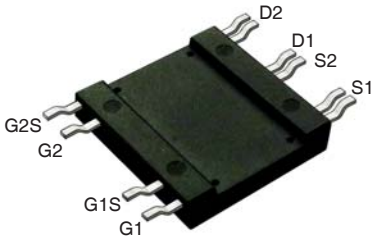
MMIX2F60N50P3

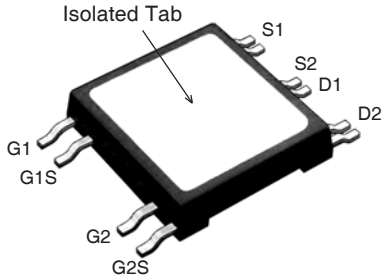
V_{DSS} = 500V
I_{D25} = 30A
$R_{DS(on)}$ ≤ 120mΩ

(Electrically Isolated Tab)

N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Rectifier







G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	500	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	500	V
V_{GSS}	Continuous	± 30	V
V_{GSM}	Transient	± 40	V
I_{D25}	T_C = 25°C	30	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	150	A
I_A	T_C = 25°C	30	A
E_{AS}	T_C = 25°C	1	J
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	35	V/ns
P_D	T_C = 25°C	320	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
V_{ISOL}	50/60 Hz, 1 Minute	2500	V~
F_C	Mounting Force	50..200 / 11..45	N/lb
Weight		8	g

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 1mA	500			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 4mA	3.0		5.0	V
I_{GSS}	V_{GS} = ±30V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			25	μA
	Note 2, T_J = 125°C			2	mA
$R_{DS(on)}$	V_{GS} = 10V, I_D = 30A, Note 1			120	mΩ

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Substrate
  - Excellent Thermal Transfer
  - Increased Temperature and Power Cycling Capability
  - High Isolation Voltage (2500V~)
- Fast Intrinsic Rectifier
- Avalanche Rated
- Low $R_{DS(ON)}$ and Q_G
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- Switch-Mode and Resonant-Mode Power Supplies
- DC-DC Converters
- Laser Drivers
- AC and DC Motor Drives
- Robotics and Servo Controls

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 20V, I_D = 30A, Note 1	35	60		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		6250		pF
C_{oss}			680		pF
C_{rss}			5		pF
R_{Gi}	Gate Input Resistance		1.0		Ω
$t_{d(on)}$	**Resistive Switching Times**		18		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 30A		16		ns
$t_{d(off)}$	R_G = 1Ω (External)		37		ns
t_f			8		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 30A		96		nC
Q_{gs}			28		nC
Q_{gd}			26		nC
R_{thJC}				0.39	°C/W
R_{thCS}			0.05		°C/W
R_{thJA}			30		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			60	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			240	A
V_{SD}	I_F = I_S, V_{GS} = 0V, Note 1			1.4	V
t_{rr}	I_F = 30A, -di/dt = 100A/μs			250	ns
I_{RM}	V_R = 100V, V_{GS} = 0V		11		A
Q_{RM}			1.0		μC

Notes:

1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Part must be heatsunk for high-temp I_{DSS} measurement.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

Fig. 1. Output Characteristics @ T_J = 25°C

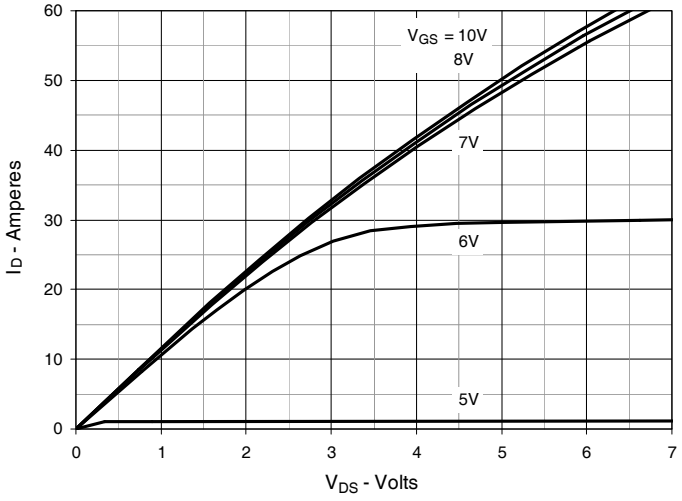


Fig. 2. Extended Output Characteristics @ T_J = 25°C

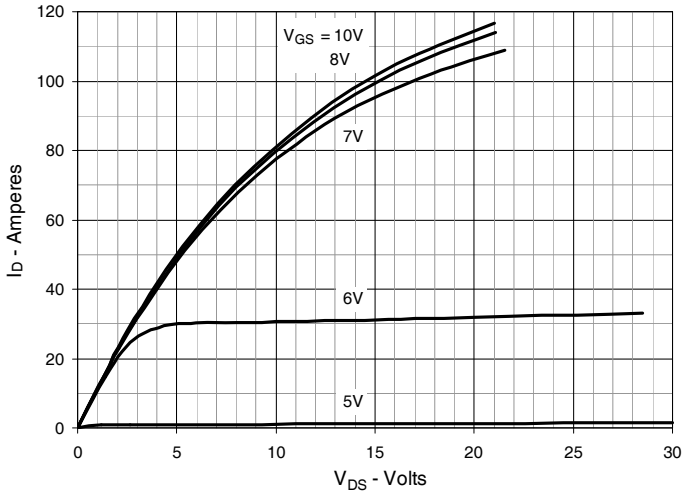


Fig. 3. Output Characteristics @ T_J = 125°C

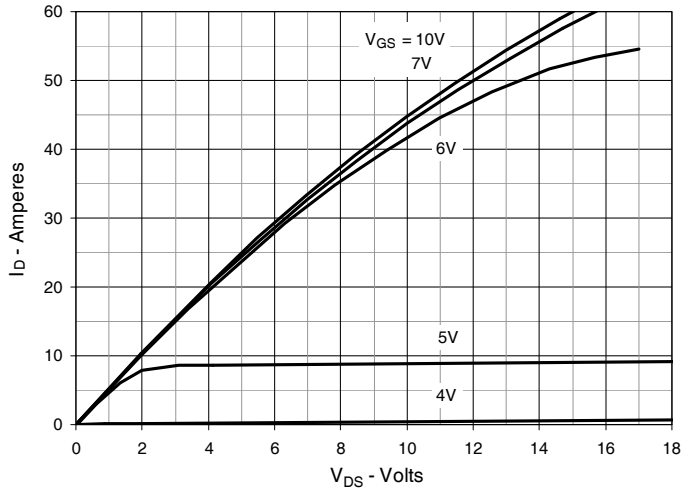


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 30A Value vs. Junction Temperature

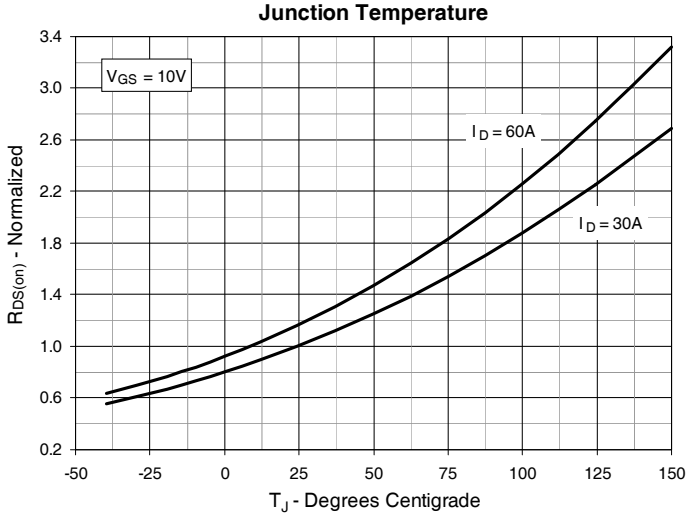


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 30A Value vs. Drain Current

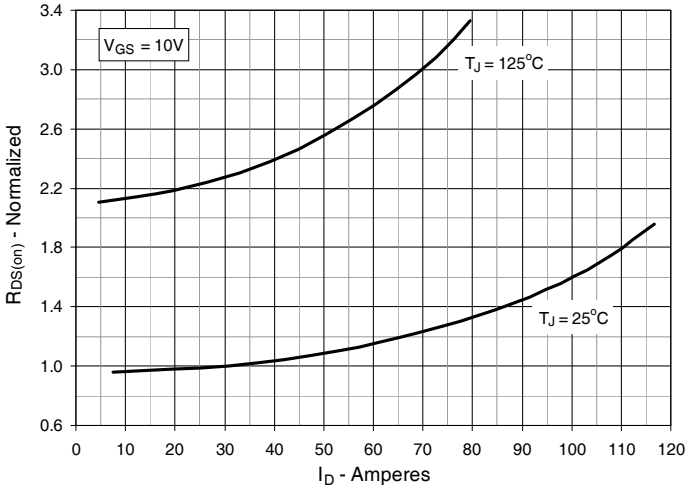


Fig. 6. Maximum Drain Current vs. Case Temperature

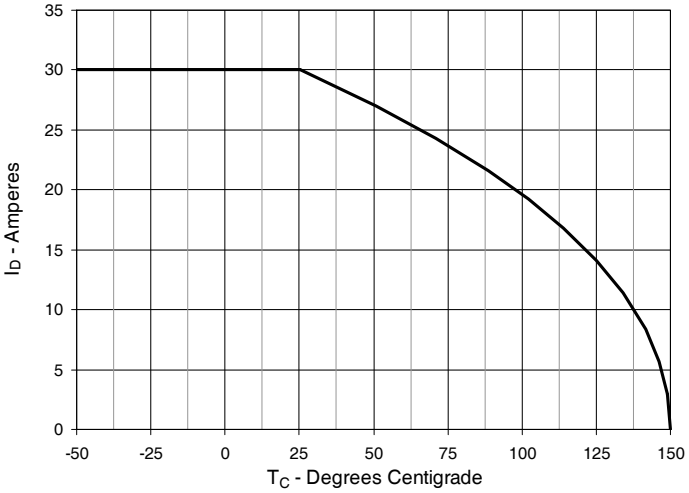


Fig. 7. Input Admittance

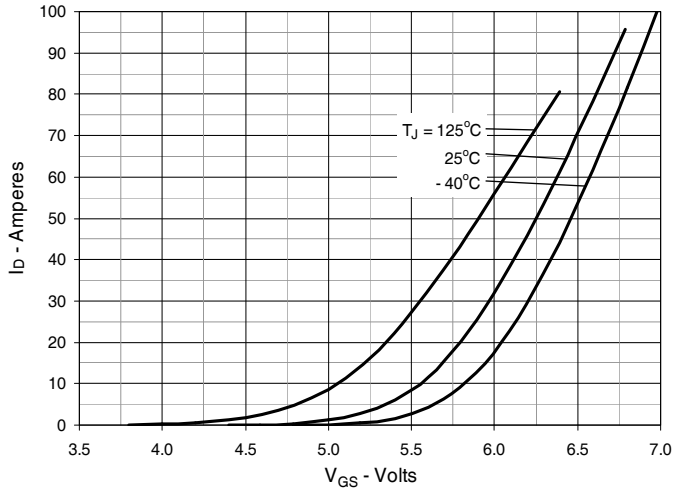


Fig. 8. Transconductance

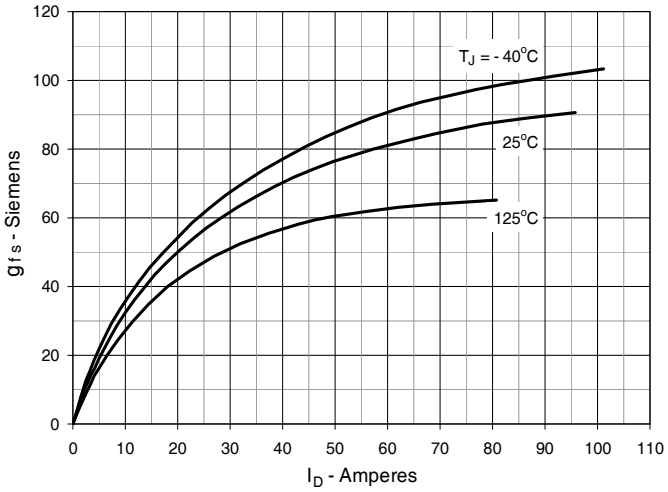


Fig. 9. Forward Voltage Drop of Intrinsic Diode

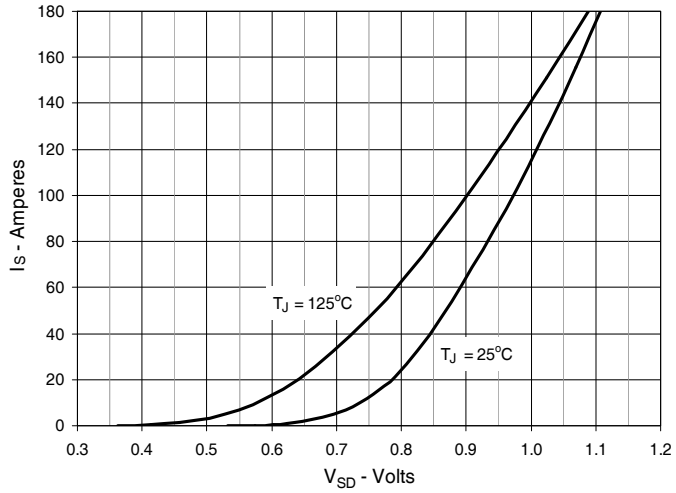


Fig. 10. Gate Charge

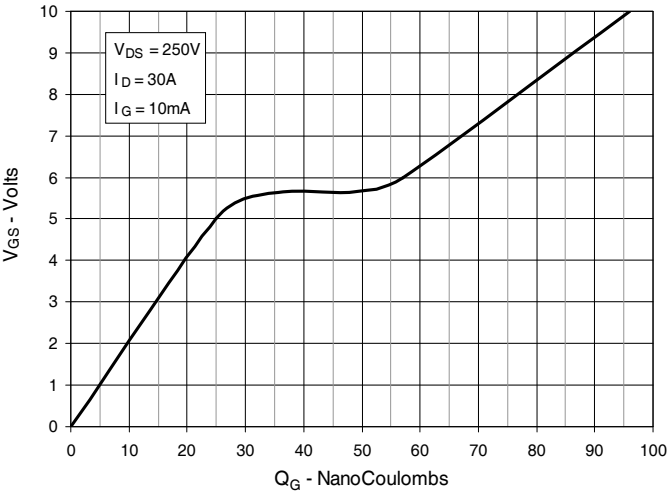


Fig. 11. Capacitance

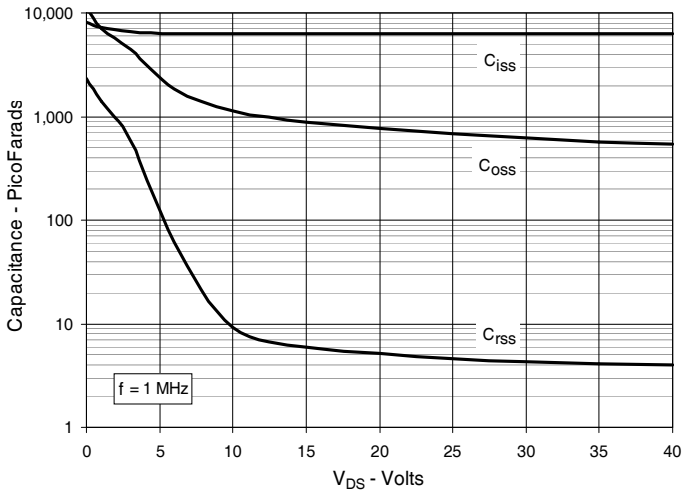


Fig. 12. Forward-Bias Safe Operating Area

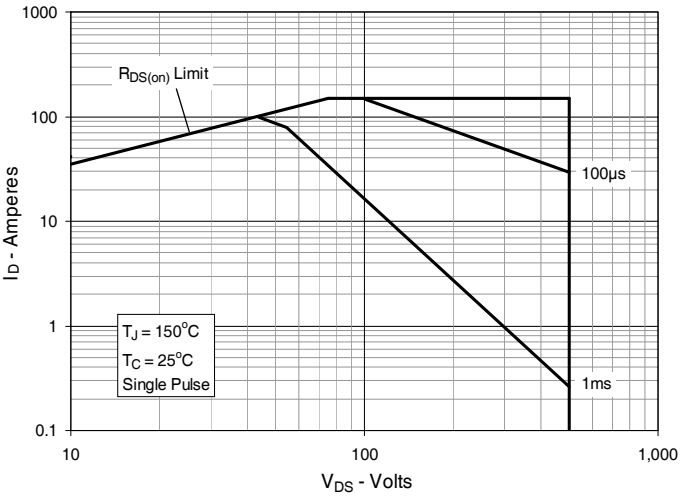
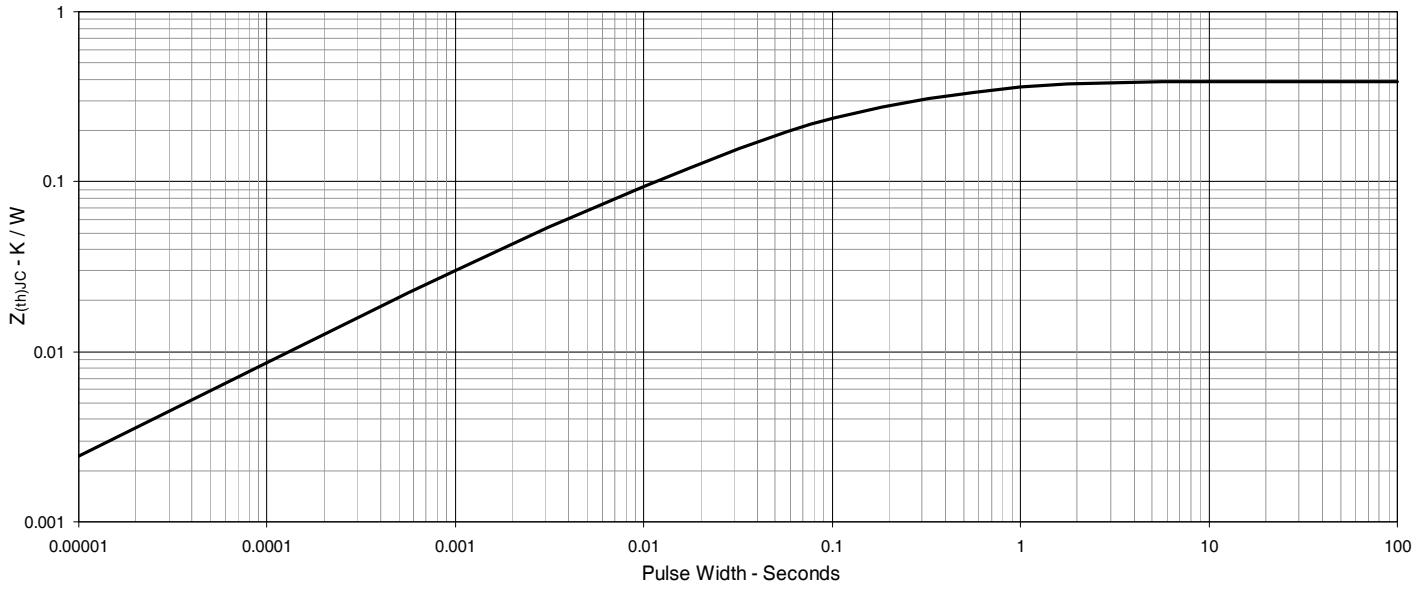
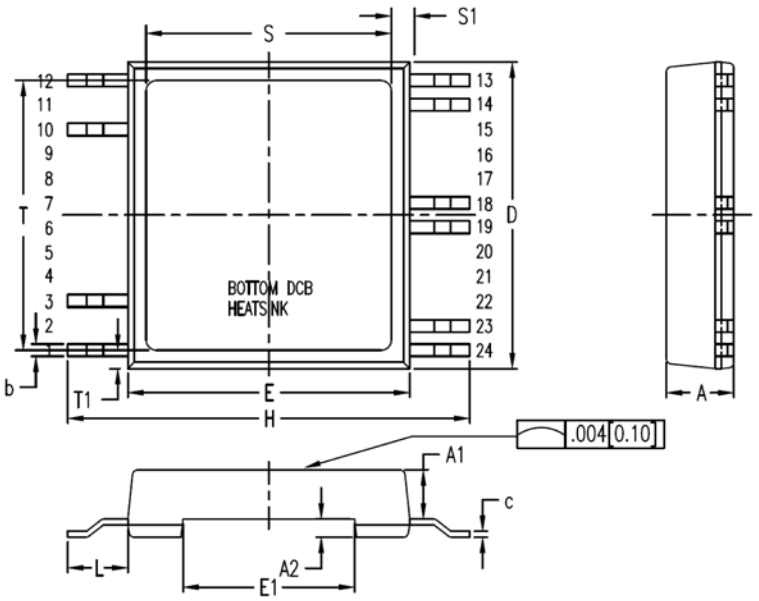


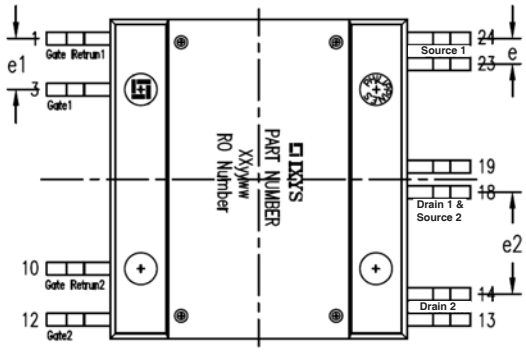
Fig. 13. Maximum Transient Thermal Impedance

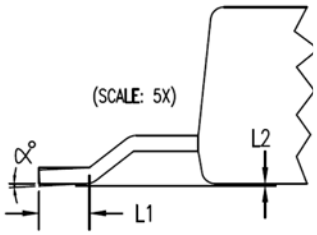


SMPD OUTLINE



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.209	.224	5.30	5.70
A1	.154	.161	3.90	4.10
A2	.055	.063	1.40	1.60
b	.035	.045	0.90	1.15
c	.018	.026	0.45	0.65
D	.976	.994	24.80	25.25
E	.898	.915	22.80	23.25
E1	.543	.559	13.80	14.20
e	.079 BSC		2.00 BSC	
e1	.157 BSC		4.00 BSC	
e2	.315 BSC		8.00 BSC	
H	1.272	1.311	32.30	33.30
L	.181	.209	4.60	5.30
L1	.051	.067	1.30	1.70
L2	.000	.006	0.00	0.15
S	.748	.807	19.00	20.50
S1	.039	.079	1.00	2.00
T	.826	.886	21.00	22.50
T1	.039	.079	1.00	2.00
∝	0	4°	0	4°





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